



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Harrison et al.

Serial No.: 10/072,743

Filed: February 7, 2002

For: METHOD OF FABRICATING AN
INTEGRATED CIRCUIT PACKAGE

Confirmation No.: 4046

Examiner: D. Nguyen

Group Art Unit: 3729

Attorney Docket No.: 2269-3758.2US
(97-0153.01/US)

Notice of Allowance Mailed:

April 26, 2004

Express Mail Mailing Label No.: EL 994842523 US

Date of Deposit with USPS: July 21, 2004

Person making Deposit: Christopher Haughton

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Title appear on page 3 of this paper.

Amendments to the Specification begin on page 4 of this paper.

Amendments to the Abstract appear on page 7 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 8 of this paper.

Remarks begin on page 12 of this paper.

IN THE TITLE:

The title was previously amended by Amendment dated November 5, 2003. Pursuant to 37 C.F.R. §§ 1.121 and 1.25 (as amended to date), please enter the title as previously amended (shown below):

~~RADIUSED LEADFRAME~~
METHOD OF FABRICATING AN INTEGRATED CIRCUIT PACKAGE